

12-18-01

Docket No. TS01-1372

A

THE COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: HARRY CHUANG

Application: LOCALIZED SLOTS FOR STRESS RELIEVE IN COPPER

10/01/01  
j1003 U.S. PTO  
10/01/01  
17955

Enclosed are:

**2** sheets of drawing(s) - formal.

An assignment of the invention to **Taiwan Semiconductor Manufacturing Company**

An associate power of attorney  Applicant claims small entity status

Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

(Col. 1)		(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 740.
TOTAL CLAIMS	46 -20=	26	x 18 =	\$ 468.
INDEP CLAIMS	2 -3=	0	x 84 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED		+ 260 =		
			SUB TOTAL	\$ 1,208.
			ASSIGNMENT	\$40.
			TOTAL	\$ 1,248.

Please charge my Deposit Account No. 19-0033 in the amount of **\$ 1,248**. A duplicate